

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An imaging apparatus comprising:

an imaging portion in which a cover glass is adhered to an imaging surface side of a solid-state image pickup device as if sandwiching leads, a slight air gap is formed between the cover glass and the imaging surface of the solid-state image pickup device and a circumference of the cover glass is larger than the solid-state image pickup device, and

a circuit board having an accommodation concave portion for accommodating the solid-state image pickup device so as to connect the leads to terminals on an upper edge of the accommodation concave portion,

wherein the concave portion forms a clearance between an adhesion area between the solid state image sensor and the cover glass, and an adhesion area between the cover glass and the circuit board;

wherein the ~~circumference of~~adhesion area between the cover glass and the circuit board adheres to the circuit board in a state of sealing the accommodation concave portion.

2-5. (Canceled)